

IN THE CLAIMS

1-8 (Canceled)

9. (Previously Presented) A circuit device, comprising:
a dielectric substrate
at least one conductive pattern formed in the dielectric substrate;
a first earthed conductor formed on a first surface of the dielectric substrate,
wherein the first earthed conductor does not cover the entire area of the first surface; and
a second earthed conductor formed on a second surface of the dielectric substrate,
the second surface opposed to the first surface, wherein the first earthed conductor is connected
with the second earthed conductor.

Claims 10-28 (Canceled)

29. (New) A circuit device, comprising:
a dielectric substrate
at least one conductive pattern formed in the dielectric substrate;
a first earthed conductor formed on a first surface of the dielectric substrate,
wherein the first earthed conductor does not cover the entire area of the first surface; and
a second earthed conductor formed on a second surface of the dielectric substrate,
the second surface opposed to the first surface, wherein the first earthed conductor is connected
with the second earthed conductor only along the periphery of the dielectric substrate.